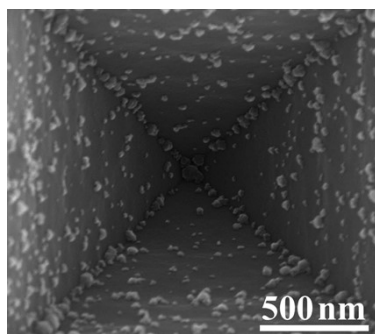
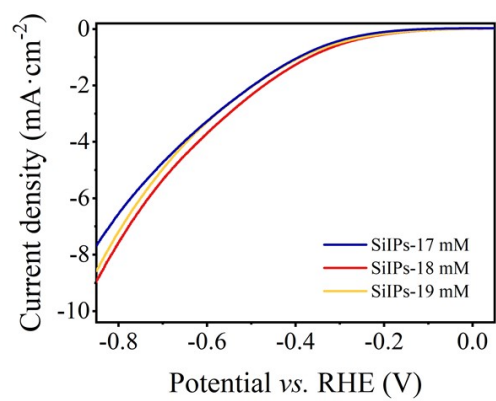


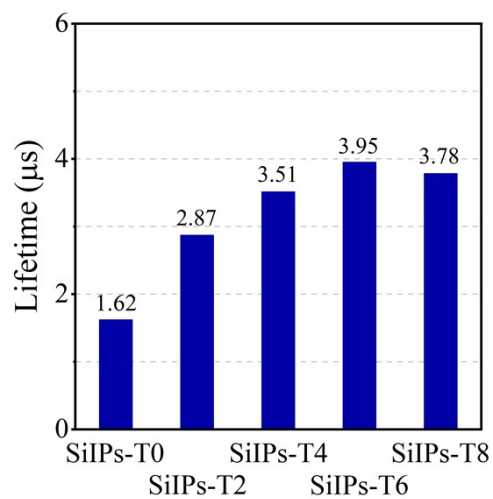
## Supporting Information



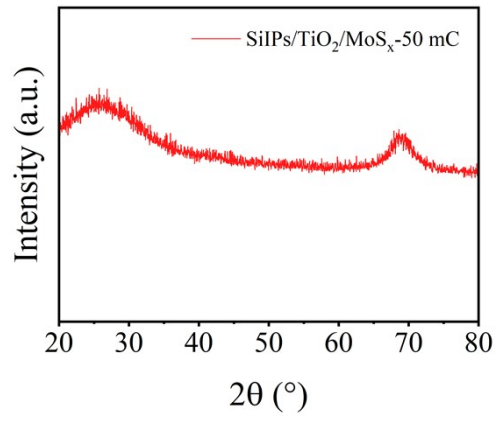
**Figure S1.** Microscopy for Cu NPs-coated sidewalls of SiIP wafers etched with Cu<sup>2+</sup> (18 mM)-containing etchant.



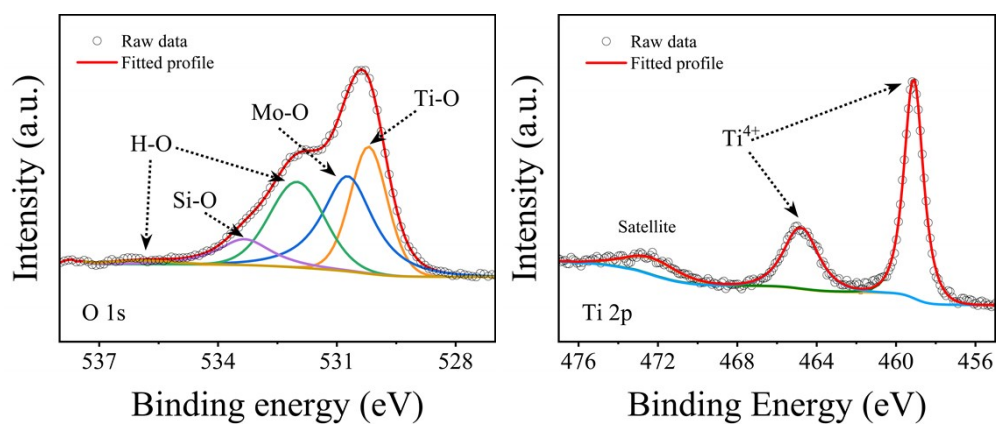
**Figure S2.** *J-V* curves for pristine SiIP photocathodes (under one sun illumination).



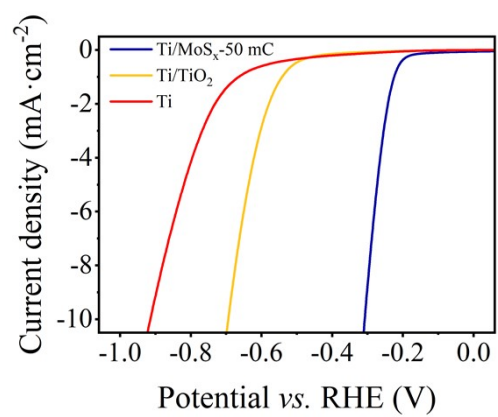
**Figure S3.** Minority carrier lifetime results for various TiO<sub>2</sub>/SiIPs/TiO<sub>2</sub> wafers.



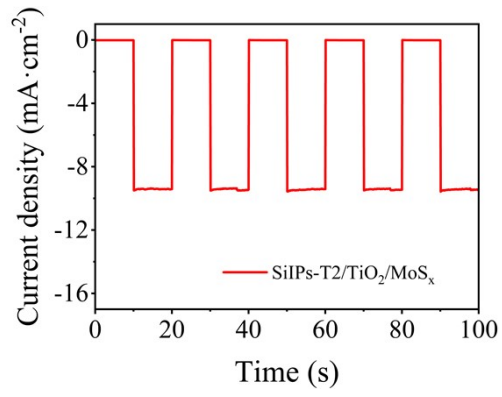
**Figure S4.** XRD patterns of SiIPs-T2/TiO<sub>2</sub>/MoS<sub>x</sub>-50 mC photocathodes.



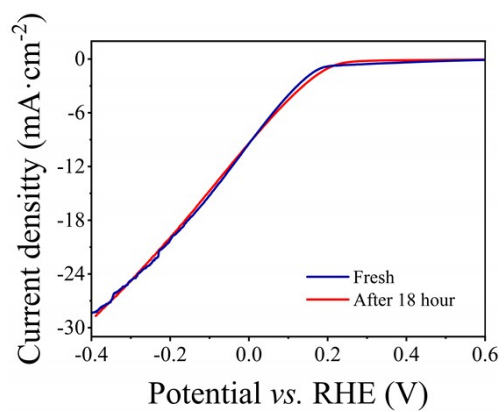
**Figure S5.** XPS spectra of SiIPs-T2/TiO<sub>2</sub>/MoS<sub>x</sub>-50 mC photocathodes in O 1s and Ti 2p regions.



**Figure S6.** *J-V* curves for cocatalysts-coated Ti electrodes (in the dark).



**Figure S7.** *J-t* curve for SiIPs-T2/TiO<sub>2</sub>/MoS<sub>x</sub>-50 mC photocathode (under chopped one sun illumination).



**Figure S8.** *J-V* curves comparisons for SiIPs-T2/TiO<sub>2</sub>/MoS<sub>x</sub>-50 mC cathode test before and after 18 h-long PEC catalysis.



**Table S1.** Mean reflectivity results of various (TiO<sub>2</sub>-coated) SiIP photocathodes.

TiO <sub>2</sub> deposition	SiIPs-T0	SiIPs-T2	SiIPs-T4	SiIPs-T6	SiIPs-T8	Planar Si
w/o TiO <sub>2</sub> layer	5.87%	9.59%	13.58%	13.99%	15.44%	38.74%
w TiO <sub>2</sub> layer	3.90%	6.60%	9.00%	10.38%	12.18%	29.69%

**Table S2.** Fitting results of EIS data for various SiIP electrodes.

Photocathode	$R_s$ ( $\Omega \text{ cm}^2$ )	$R_{ct1}$ ( $\Omega \text{ cm}^2$ )	$R_{ct2}$ ( $\Omega \text{ cm}^2$ )	$R_{ct3}$ ( $\Omega \text{ cm}^2$ )
SiIPs-T2	27.69	N/A	N/A	3109.4
SiIPs-T2/TiO <sub>2</sub>	17.56	5.76	15.37	57.36
SiIPs-T2/TiO <sub>2</sub> /M.S	17.9	6.15	10.72	16.33

EIS data are fitted using an equivalent circuit with three constant phase elements (CPEs) and four resistive components, as shown in the inset of Fig. 7b. Among them,  $R_s$  represents electrolyte resistance.  $R_{ct1}$  is interfacial charge transfer resistance at Si/TiO<sub>2</sub> interface, while  $R_{ct2}$  means the charge diffusion resistance within TiO<sub>2</sub> layer. Besides,  $R_{ct3}$  indicates interfacial charge transfer resistance at electrode/electrolyte interface, reflecting total charge transfer capability and hydrogen evolution kinetics of Si-based electrodes.

**Table S3.** Onset potential and current density data for various SiIP electrodes.

Photocathode	Onset potential (V vs. RHE)	Current density ( mA·cm <sup>-2</sup> @0 V vs. RHE)
SiIPs-T0	-0.37	0.01
SiIPs-T2	-0.35	0.03
SiIPs-T4	-0.36	0.03
SiIPs-T6	-0.40	0.03
SiIPs-T8	-0.40	0.03
SiIPs-T0/TiO <sub>2</sub>	0.09	2.08
SiIPs-T2/TiO <sub>2</sub>	0.10	2.42
SiIPs-T4/TiO <sub>2</sub>	0.12	2.57
SiIPs-T6/TiO <sub>2</sub>	0.09	2.01
SiIPs-T8/TiO <sub>2</sub>	0.07	1.75
SiIPs-T2/TiO <sub>2</sub> /MoS <sub>x</sub> -10 mC	0.18	7.53
SiIPs-T2/TiO <sub>2</sub> /MoS <sub>x</sub> -50 mC	0.18	9.45
SiIPs-T2/TiO <sub>2</sub> /MoS <sub>x</sub> -100 mC	0.19	7.35
SiIPs-T2/TiO <sub>2</sub> /MoS <sub>x</sub> -200 mC	0.19	6.41

Note that we define onset potential as the specific RHE potential at which the photocurrent density reaches up to 1 mA·cm<sup>-2</sup>.